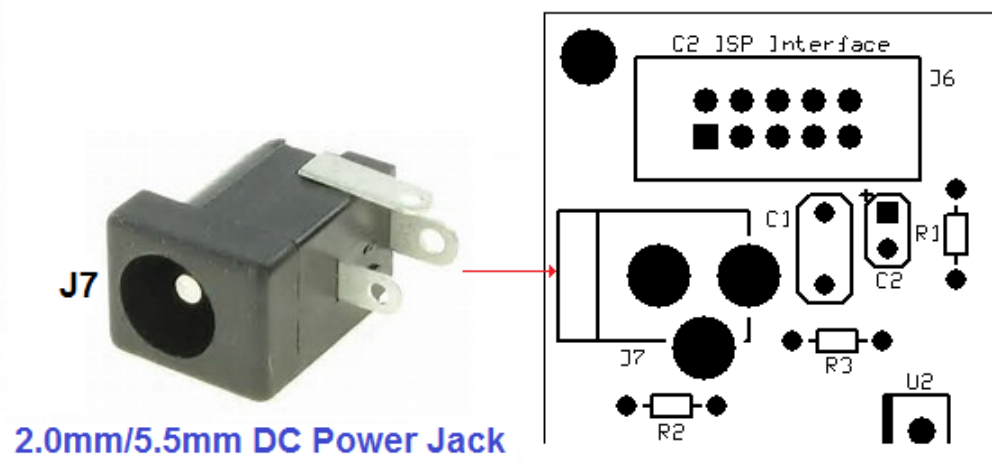

Figure 5

11) Secure DC power jack J7 in place with painter's tape and solder it into position. (Trimming the leads of this component is not necessary). Perform a solder bridge check.

12) Referring to Table 3 of the Tables and Figures sheets, remove Polyswitch resettable fuse PTC1 from the C8051F330GM Development Board kit package. Insert PTC1 into position using Figure 6 on the next page as a guide.

NOTE: PTC1 and PTC2 are not polarized, so these components can be positioned in either orientation.

13) Secure PTC1 in place with painter's tape and solder it into position. Also trim the component leads and perform a solder bridge check.

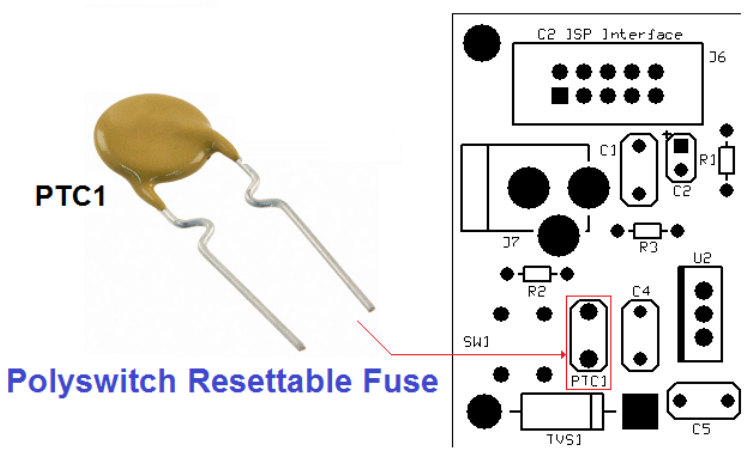

Figure 6

14) Referring to Table 3 of the Tables and Figures sheets, remove circuit board indicator LED1 from the C8051F330GM Development Board kit package. Insert the LED into the PCB using Figure 7 below as a guide.

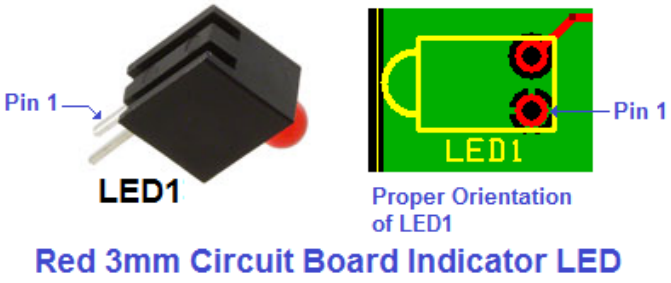

Figure 7

15) Secure LED1 in place with painter's tape and solder it into position. Also trim the component leads and perform a solder bridge check.

16) Referring to Table 3 of the Tables and Figures sheets, remove the six two-position headers from the C8051F330GM Development Board kit package. Insert these headers into position using Figure 8 below as a guide.

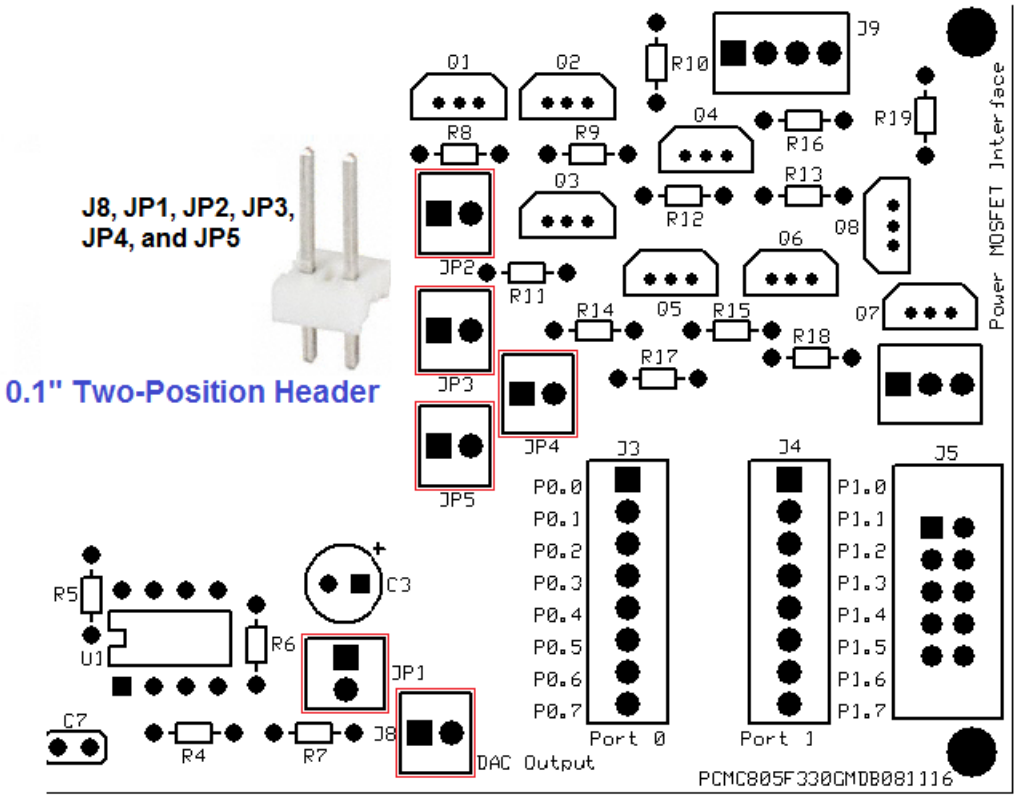

Figure 8

17) Secure the six two-position headers in place with painter's tape and solder them into position. Also trim the component leads and perform a solder bridge check.

18) Referring to Table 3 of the Tables and Figures sheets, remove the three-position header from the C8051F330GM Development Board kit package. Insert the header into the J10 position using Figure 9 on the following page as a guide.

19) Secure three-position header J10 in place with painter's tape and solder it into position. Also trim the component leads and perform a solder bridge check.

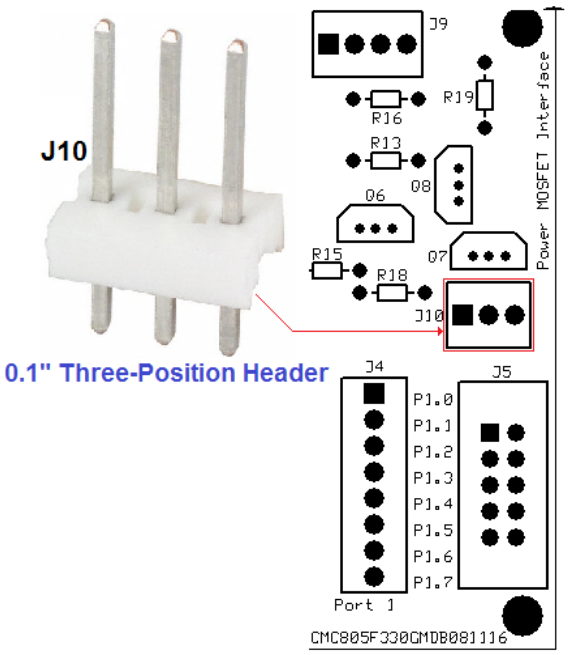

Figure 9

20) Referring to Table 3 of the Tables and Figures sheets, remove four-position header J9 from the C8051F330GM Development Board kit package. Insert the header into the J9 position using Figure 10 below as a guide.

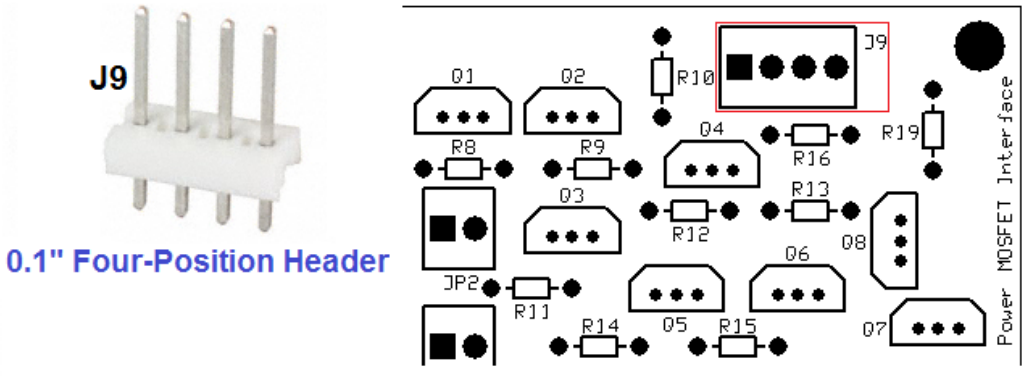

Figure 10

21) Referring to Table 3 of the Tables and Figures sheets, remove the two eight-position headers J3 and J4 from the C8051F330GM Development Board kit package. Insert the two headers into position using Figure 11 below as a guide.

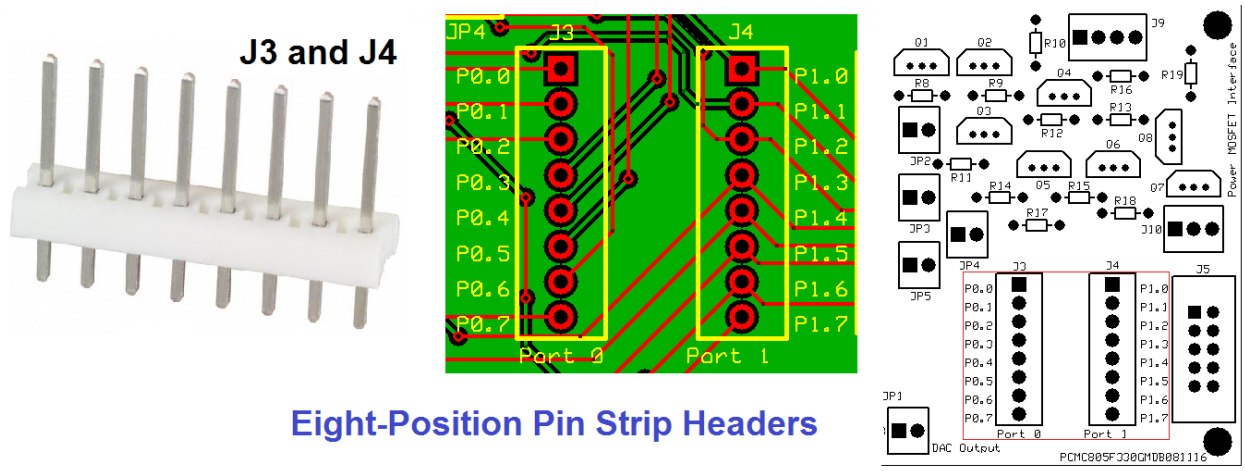

Figure 11

22) Secure headers J3 and J4 in place with painter's tape and solder them into position. Also trim the component leads and perform a solder bridge check.

23) Referring to Table 3 of the Tables and Figures sheets, remove the two ten-position, dual-row JTAG connectors J5 and J6 from the C8051F330GM Development Board kit package. Using Figure 12 below as a guide, insert the two JTAG connectors into position.

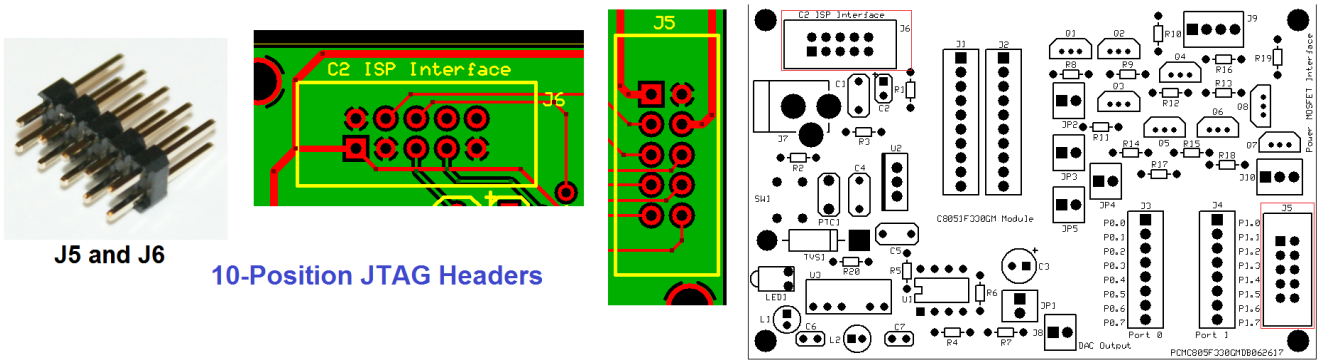

Figure 12